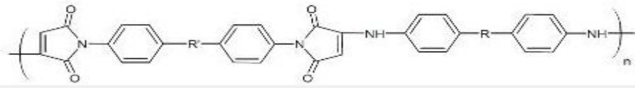
PIR-003 Polyimide Resin Powder

PIR-003 polyimide resin powder is unfilled soluble polyimide with bismaleimide structure and particle size: 300mesh, widely used as matrix resin for reinforcement prepreg of fibers, mixture with epoxy for heat resistance, membrane, etc.

Note: Different polyimide types also available with different structures

Base structure:



Properties:

Visual/Solubility	Fine yellow powder/soluble in DMF,NMP,etc.
Purity%	Over 98.5
Gravity	1.32g/cm^3
Gelling time(170℃)	200--500s
Curing temperature(℃)/Pressure(MPa)	220-230/30-60
Softening temperature（℃）	90-120
Martin temperature（℃）	260
TGA260（℃）24hr/300（℃）24hr	Less 1.5% (mainly moisture loss)
Tg（℃）	330
Tensile strength(MPa)	113.4
Elongation%	Over 5%
Surface resistivityΩ	1 x 10^{15}
Dieletric consistant	3.5

Packing: carton after sealed by plastic film bag Shelf life: 2 Years

Note: 1.Since polyimide resins are hygroscopic, please predried at 250 °F (120 °C) for a couple of hours before any use

2.All of above information is based on our best knowledge, not read as guarantees. Right reserved for corrections.

3.Please contact us if customization requirements.

Contact information:

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